

BY228

PRV : 1500 Volts

Io : 3.0 Ampere

FEATURES :

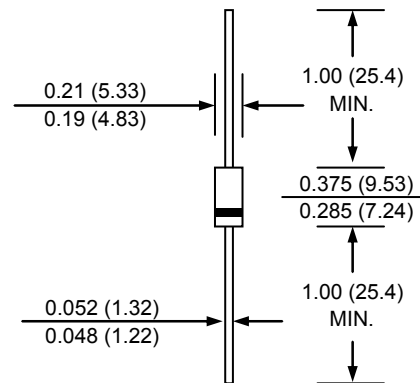
- * Glass passivated chip
- * High current capability
- * High maximum operating temperature
- * Low reverse current
- * **Pb / RoHS Free**

MECHANICAL DATA :

- * Case : DO-201AD Molded plastic
- * Epoxy : UL94V-O rate flame retardant
- * Lead : Axial lead solderable per MIL-STD-202, Method 208 guaranteed
- * Polarity : Color band denotes cathode end
- * Mounting position : Any
- * Weight : 1.148 grams

DAMPER DIODE

DO - 201AD



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temperature unless otherwise specified
 Single phase, half wave, 60 Hz, resistive or inductive load
 For capacitive load, derate current by 20%

RATING	SYMBOL	VALUE	UNIT
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1650	V
Maximum Continuous Reverse Voltage	V_R	1500	V
Maximum Average Forward Current	$I_{F(AV)}$	3.0	A
Maximum Non-Repetitive Peak Forward Current ($t_p = 10ms$, Half Sine wave)	I_{FSM}	50	A
Maximum Forward Voltage at $I_F = 5 A$.	V_F	1.5	V
Maximum Reverse Current at $V_R = 1500 V$, $T_j = 25\text{ }^\circ\text{C}$ at $V_R = 1500 V$, $T_j = 140\text{ }^\circ\text{C}$	I_R	5.0	μA
	$I_{R(H)}$	140	μA
Maximum Reverse Recovery time (Note 1)	T_{rr}	2.0	μs
Thermal Resistance Junction to Ambient (Note 2)	$R_{\theta JA}$	70	K/W
Junction Temperature Range	T_j	140	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	- 55 to + 175	$^\circ\text{C}$

Notes :

- (1) Reverse Recovery Test Conditions : $I_F = 0.5 A$, $I_R = 1.0 A$, $I_{rr} = 0.25 A$.
- (2) On PC board with spacing 25 mm

RATING AND CHARACTERISTIC CURVES (BY228)

FIG.1 - MAX. AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

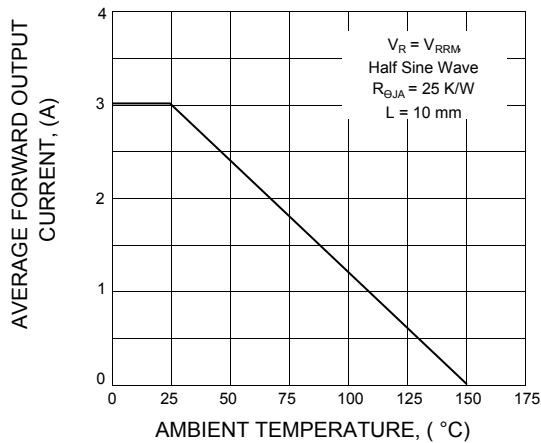


FIG.2 - TYP. THERMAL RESISTANCE VS. LEAD LENGTH

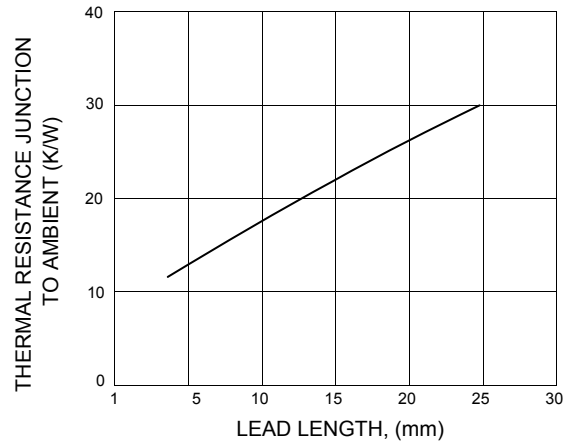


FIG.3 - FORWARD CURRENT VS. FORWARD VOLTAGE

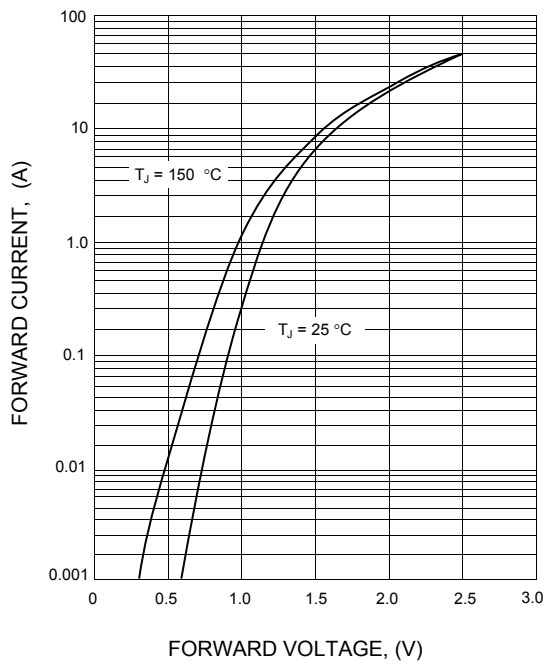


FIG.4 - REVERSE CURRENT VS. JUNCTION TEMPERATURE

